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## DEI1022, DEI1023 DEI1024, DEI1025 ARINC 429 Line Driver Integrated Circuit

### Features

- ARINC 429 Line Driver for high speed (100 KHz) and low speed (12.5 KHz) data rates.
- Adjustable Slew rates via external capacitors.
- Small foot print (14L SOIC NB)
- Programmable output differential range via  $V_{REF}$  pin.
- Drives full ARINC load of 400  $\Omega$  and 30 nF.
- -55 °C to +85 °C operating temperature range.
- 100% Final testing.



### Functional Description

The ARINC 429 Line Driver Circuit is a bipolar monolithic IC designed to meet the requirements of several general aviation serial data bus standards. These include the differential bipolar RZ types such as ARINC 429, ARINC 571, and ARINC 575.

The DEI1022, DEI1023, DEI1024, and DEI1025 are a family of ARINC Line Driver circuits with variations in driver output resistance and output fusing. See the Product Matrix definition table below to find the correct version for your application.

Serial data is presented on DATA(A) and DATA(B) logic inputs in the dual rail format of the DEI1016. The driver is enabled by the SYNC and CLOCK inputs. The output voltage level is programmed by the  $V_{REF}$  input and is normally tied to +5VDC along with  $V_1$  to produce output levels of +5 volts, 0 volts, and -5 volts on each output for  $\pm 10$  volt differential outputs.

The driver output resistance of the DEI1022 and DEI1023 is 75 $\Omega$  at room temperature; 37.5 $\Omega$  on each output. The driver output resistance of the DEI1024 and the DEI1025 is zero. The output slew rate is controlled by external timing capacitors on  $C_A$  and  $C_B$ . Typical values are 75pF for 100KHz and 500pF for 12.5KHz data.

Table 1: Product Matrix		
Part Number	Output Fusing	Output Resistance (each output)
DEI 1022	NO	37.5 $\Omega$
DEI 1023	YES	37.5 $\Omega$
DEI 1024	NO	0 $\Omega$
DEI 1025	YES	0 $\Omega$

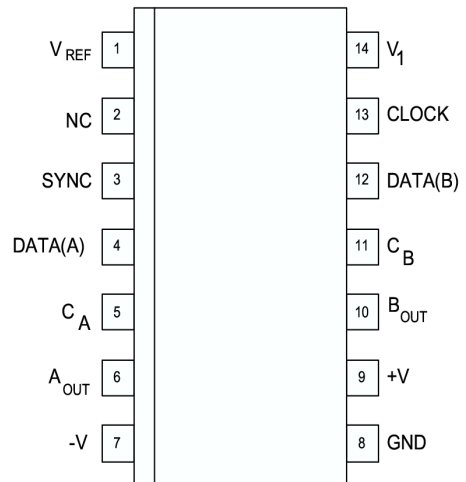


Figure 1 Pinout

Pin #	Pin Name	Table 2: Pin Descriptions
1	V <sub>REF</sub>	Analog Input. The voltage on V <sub>REF</sub> sets the output voltage levels on A <sub>OUT</sub> and B <sub>OUT</sub> . The output logic levels swing between +V <sub>REF</sub> , 0 volts, and -V <sub>REF</sub> volts.
2	NC	No Connect
3	SYNC	Logic input. Logic 0 forces outputs to NULL state. Logic 1 enables data transmission.
13	CLOCK	Logic input. Logic 0 forces outputs to NULL state. Logic 1 enables data transmission.
4 12	DATA(A) DATA(B)	Logic inputs. These signals contain the Serial Data to be transmitted on the ARINC 429 data bus
5 11	C <sub>A</sub> C <sub>B</sub>	Analog Nodes. External timing capacitors are tied from these points to ground to establish the output signal slew rate. Typical C <sub>A</sub> = C <sub>B</sub> = 75pF for 100 kHz data and C <sub>A</sub> = C <sub>B</sub> = 500pF for 12.5 kHz data.*
6 10	A <sub>OUT</sub> B <sub>OUT</sub>	Outputs. These are the line driver outputs which are connected to the aircraft serial data bus.
7	-V	Negative Supply Input. -15VDC nominal.
8	GND	Ground.
9	+V	Positive Supply Input. +15VDC nominal.
14	V <sub>1</sub>	Logic Supply Input. +5VDC nominal.

\*C<sub>A</sub> and C<sub>B</sub> pin voltages swing between +/-5 volts. Any electronic switching of the capacitor on the pins must not inhibit the full voltage swings.

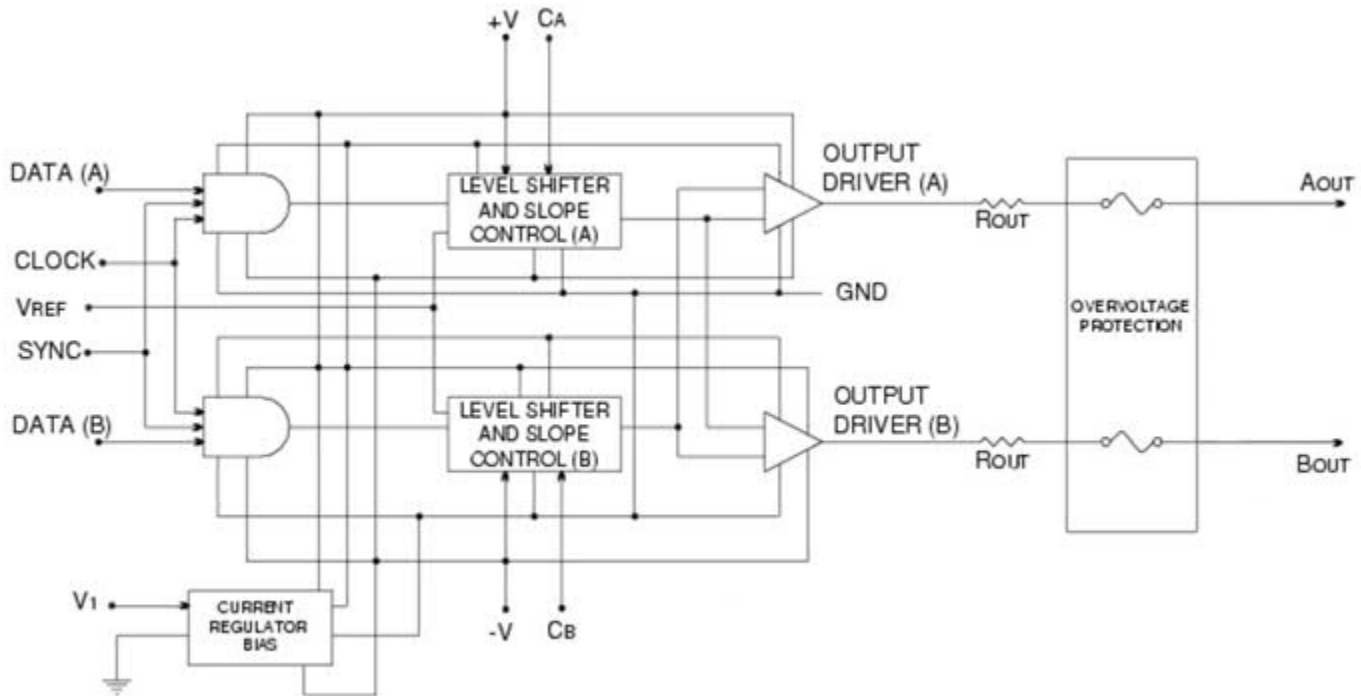


Figure 2 Function Diagram

Table 3: Truth Table						
INPUTS				OUTPUTS		
SYNC	CLOCK	DATA(A)	DATA(B)	A <sub>OUT</sub>	B <sub>OUT</sub>	STATE
L	X	X	X	0	0	NULL
X	L	X	X	0	0	NULL
H	H	L	L	0	0	NULL
H	H	H	H	0	0	NULL
H	H	H	L	+V <sub>REF</sub>	-V <sub>REF</sub>	ONE
H	H	L	H	-V <sub>REF</sub>	+V <sub>REF</sub>	ZERO

**NOTE:** X = Don't Care

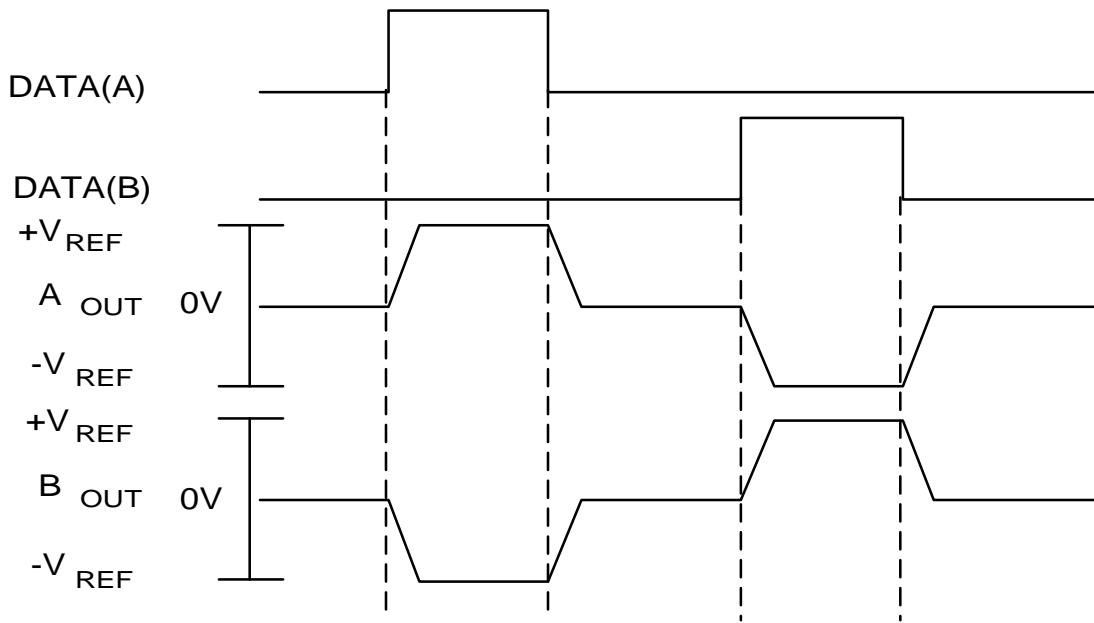


Figure 3 Input / Output Waveforms

# Electrical Characteristics

**Table 4: Absolute Maximum Ratings**

PARAMETER	SYMBOL	RATING	UNITS
Voltage between pins +V and -V		40	V
V1 Maximum Voltage	V <sub>1</sub>	7	V
VREF Maximum Voltage	V <sub>REF</sub>	6	V
Logic Inputs		(GND-0.3V) to (V1 + 0.3V)	V
Peak Body Temperature		260	°C
Storage Temperature	T <sub>STG</sub>	-65 to +150	°C
Max Junction Temperature Die Limit (short term operation)	T <sub>J MAX1</sub>	+175	°C
Max Junction Temperature Plastic Package Limit (prolonged operation)	T <sub>J MAX2</sub>	+145	°C
Output Short Circuit Duration	See Note 1		
Output Over-Voltage Protection	See Note 2		
Power Dissipation	See Table 6		

**Notes:**

1. One output at a time can be shorted to ground indefinitely. Both outputs can be shorted indefinitely to ground or to each other for T<sub>A</sub> < 45° C and Data Duty Cycle < 40%.
2. Both DEI1023 and DEI1025 outputs are fused at between 0.5 Amp DC and 1.0 Amp DC to prevent an over-voltage fault from coupling onto the system power bus. The DEI1022 and DEI1024 outputs are not fused. External fusing must be provided to meet the Transmitter Fault Isolation of the ARINC 429 Specification.

**Table 5: Operating Conditions**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS
Positive Supply Voltage	+V	+11.4		+16.5	V
Negative Supply Voltage	-V	-11.4		-16.5	V
V1	V <sub>1</sub>	+4.75	+5	+5.25	V
VREF (For ARINC 429)	V <sub>REF</sub>	+4.75	+5	+5.25	V
Operating Temperature	T <sub>A</sub>	-55		+85	°C

**Table 6: Power Dissipation**

100% Duty Cycle, Full Load = 400Ω / 30nF, Half Load = 4,000Ω / 10nF						
DATA RATE	LOAD	+V @ 15V	-V @ -15V	V1, VREF @ 5V	Pd POWER	LOAD POWER
0 to 100kbps	NONE	2 mA	5 mA	4 mA	125 mW	0 mW
12.5kbps	FULL	16 mA	19 mA	4 mA	485 mW	60 mW
100kbps	FULL	48 mA	51 mA	4 mA	1194 mW *	325 mW
12.5kbps	HALF	6 mA	8 mA	4 mA	196 mW	30 mW
100kbps	HALF	22 mA	25 mA	4 mA	561 mW	162 mW

**Note:** \* May require heat sink @ T<sub>A</sub> = +85 °C

**Table 7: DC Electrical Characteristics**

**Conditions:** Temperature: -55°C to +85°C, +V = +11.4 V to +16.5 V, -V = -11.4 V to -16.5 V, V<sub>1</sub> = V<sub>REF</sub> = +5 V ±5%

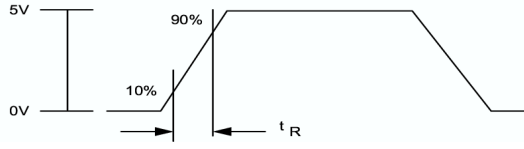
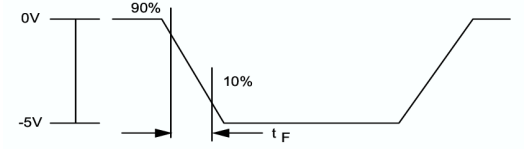
SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT	TEST CONDITIONS
IQ+V	Quiescent +V supply current	-	2	-	mA	No Load. DATA = CLOCK = SYNC = LOW
IQ-V	Quiescent -V supply current	-	5	-	mA	No Load. DATA = CLOCK = SYNC = LOW
IQV <sub>1</sub>	Quiescent V <sub>1</sub> supply current	-	4	-	mA	No Load. DATA = CLOCK = SYNC = LOW
IQV <sub>REF</sub>	Quiescent V <sub>REF</sub> supply current	-	10	-	uA	No Load. DATA = CLOCK = SYNC = LOW
V <sub>IH</sub>	Logic 1 Input V	2.0	-	-	V	No Load.
V <sub>IL</sub>	Logic 0 Input V	-	-	0.6	V	No Load.
I <sub>IH</sub>	Logic 1 Input I	-	-	10	uA	V <sub>IH</sub> = 2.0V
I <sub>IL</sub>	Logic 0 Input I	-	-	-20	uA	V <sub>IL</sub> = 0.6V
I <sub>OHSC</sub>	Output Short Circuit Current (Output High)	-	-	-80	mA	Short to Ground
I <sub>OLSC</sub>	Output Short Circuit Current (Output Low)	80	-	-	mA	Short to Ground
V <sub>OH</sub>	Output Voltage HIGH. (+1)	V <sub>REF</sub> - 250mV	V <sub>REF</sub>	V <sub>REF</sub> + 250mV	V	No Load.
V <sub>NULL</sub>	Output Voltage NULL. (0)	-250	-	+250	mV	No Load.
V <sub>OL</sub>	Output Voltage LOW. (-1)	-V <sub>REF</sub> - 250mV	-V <sub>REF</sub>	-V <sub>REF</sub> + 250mV	V	No Load. 429 Mode.
I <sub>CT</sub>	Timing Capacitor Charge Current	-	-	-	-	No Load. SYNC = CLOCK = HIGH CA and CB held at zero volts.
+	CA (+1) CB (-1)	-	+200	-	uA	
-	CA (-1) CB (+1)	-	-200	-	uA	
ISC (+V)	+V Short Circuit Supply Current	-	-	+150	mA	Output short to ground
ISC (-V)	-V Short Circuit Supply Current	-	-	-150	mA	Output short to ground
R <sub>OUT</sub>	Resistance on each output		See Note		Ω	Room Temp Only
C <sub>IN</sub>	Input Capacitor	-	-	15	pF	by design

**Note:** For DE11022 and DE11023, the typical resistance on each output is 30 to 45 Ω. For DE11024 and DE11025, the resistance on each output is 0 Ω.

## AC Characteristics

Figure 3 shows the output waveform for the ARINC 429. The output slew rates are controlled by timing capacitors  $C_A$  and  $C_B$ . They are charged by  $\pm 200\mu\text{A}$  (nom.). Slew rate (SR) measured as  $\text{V}/\mu\text{sec}$ , is calculated by:  

$$\text{SR} = 200/C, \text{ where } C \text{ is in pF}$$

Table 8: AC Electrical Characteristics					
Parameter	Symbol	MIN	MAX	UNITS	NOTES
Output Rise Time $A_{\text{OUT}}$ or $B_{\text{OUT}}$ $C_A = C_B = 75\text{pF}$ $C_A = C_B = 500\text{pF}$	$t_{\text{R}}$ $t_{\text{RL}}$	1.0 5	2.0 15	$\mu\text{sec}$ $\mu\text{sec}$	
Output Fall Time $A_{\text{OUT}}$ or $B_{\text{OUT}}$ $C_A = C_B = 75\text{pF}$ $C_A = C_B = 500\text{pF}$	$t_{\text{F}}$ $t_{\text{FL}}$	1.0 5	2.0 15	$\mu\text{sec}$ $\mu\text{sec}$	
Input to Output Propagation Delay	$t_{\text{PNH}}$ $t_{\text{PNL}}$	-	3.0	$\mu\text{sec}$	See Figure 4
$A_{\text{OUT}} / B_{\text{OUT}}$ Skew Spec.	-	-	500	nsec	Calculated as difference of $t_{\text{PNH}}$ and $t_{\text{PNL}}$
Note: $t_{\text{R}}$ and $t_{\text{F}}$ are production tested via $I_{\text{CT}+}$ and $I_{\text{CT}-}$ tests.					

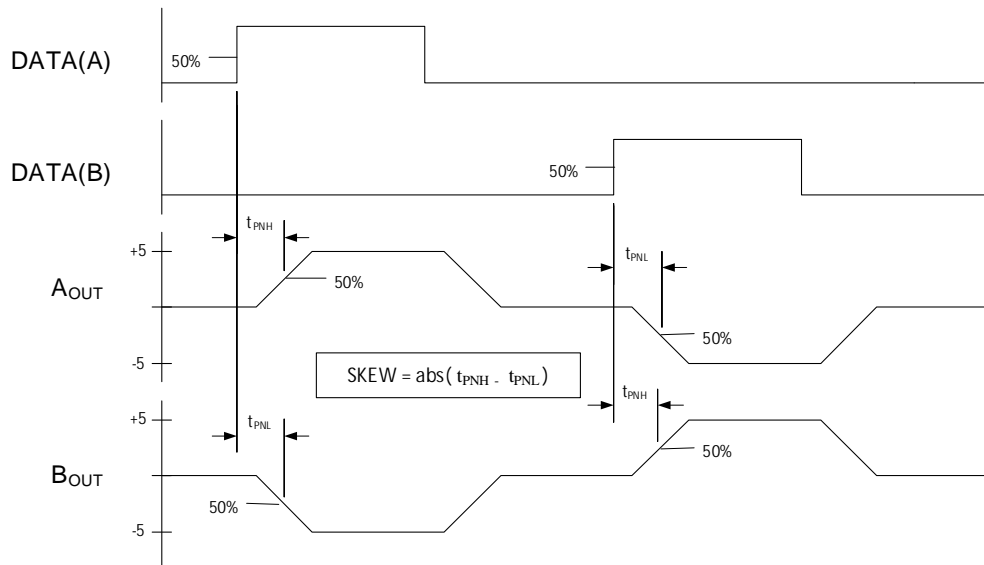


Figure 4 Propagation Delay and Skew

## Thermal Management

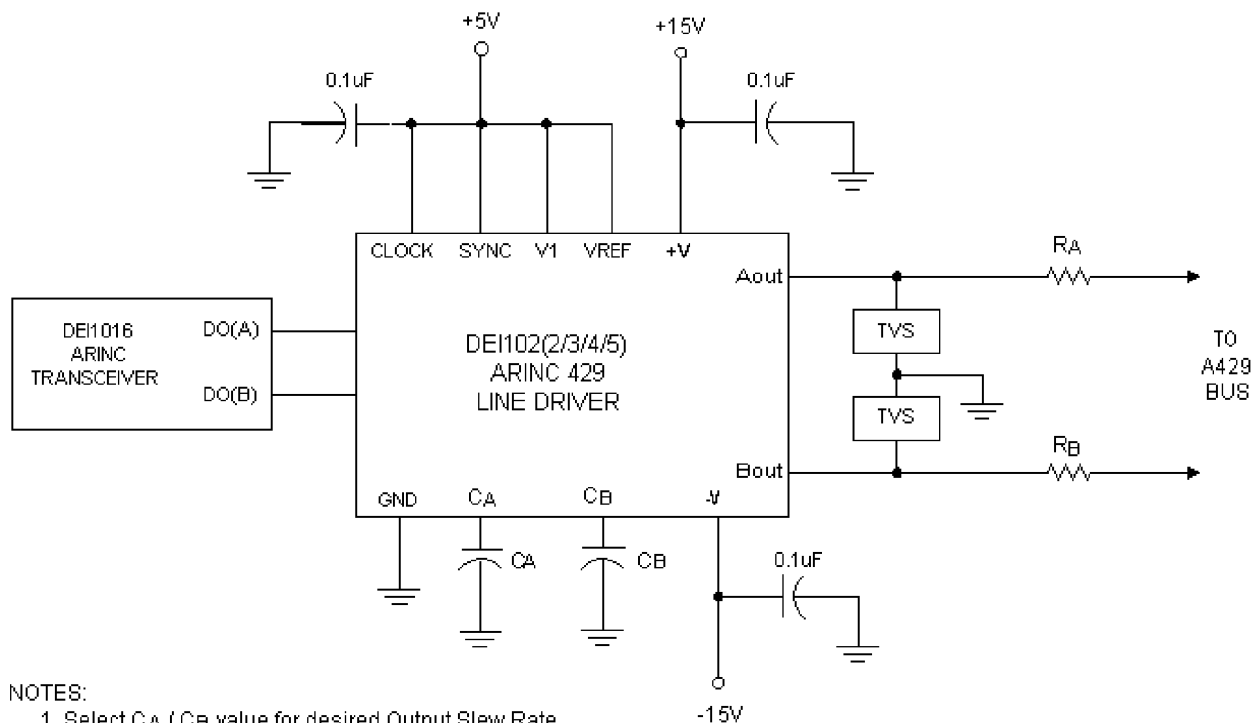
Device power dissipation varies greatly as a function of data rate, load capacitance, data duty cycle, and supply voltage. Proper thermal management is important in designs operating at the HI speed data rate (100KBS) with high capacitive loads and high data duty cycles.

Power dissipation may be estimated from Table 6 "Power Dissipation Table". Device power dissipation ( $P_d$ ) is indicated for 100% data duty cycle with no word gap null times and should be adjusted for the appropriate data duty cycle (DC).  $P_d(\text{application}) = DC * [P_d(\text{table}) - 145\text{mW}] + 145\text{mW}$ , where DC is the application data duty cycle,  $P_d(\text{table})$  is the  $P_d$  from the table for the indicated data rate and bus load, and 145mW is the quiescent power. The application's data duty cycle (DC) for 100KBS operation is calculated as:

$$\begin{aligned} DC &= \text{total bits transmitted in 10 sec period} / 1,000,000 \\ &= 32 \times \text{total ARINC words transmitted in 10 sec period} / 1,000,000 \end{aligned}$$

Heat transfer from the IC package should be maximized. Use maximum trace width on all power and signal connections at the IC. Place vias on the signal/power traces close to the IC to maximize heat flow to the internal power planes. If possible, design a solid heat spreader land under and beyond the IC to maximize heat flow from the device.

## Applications



### NOTES:

1. Select CA / CB value for desired Output Slew Rate.
2. TVS: TRANSIENT VOLTAGE SUPPRESSOR.
3. RA / RB : Use 37 Ohm for DE102(4/5). Use Zero Ohm for DE102(2/3).

**Figure 5: Typical Application**

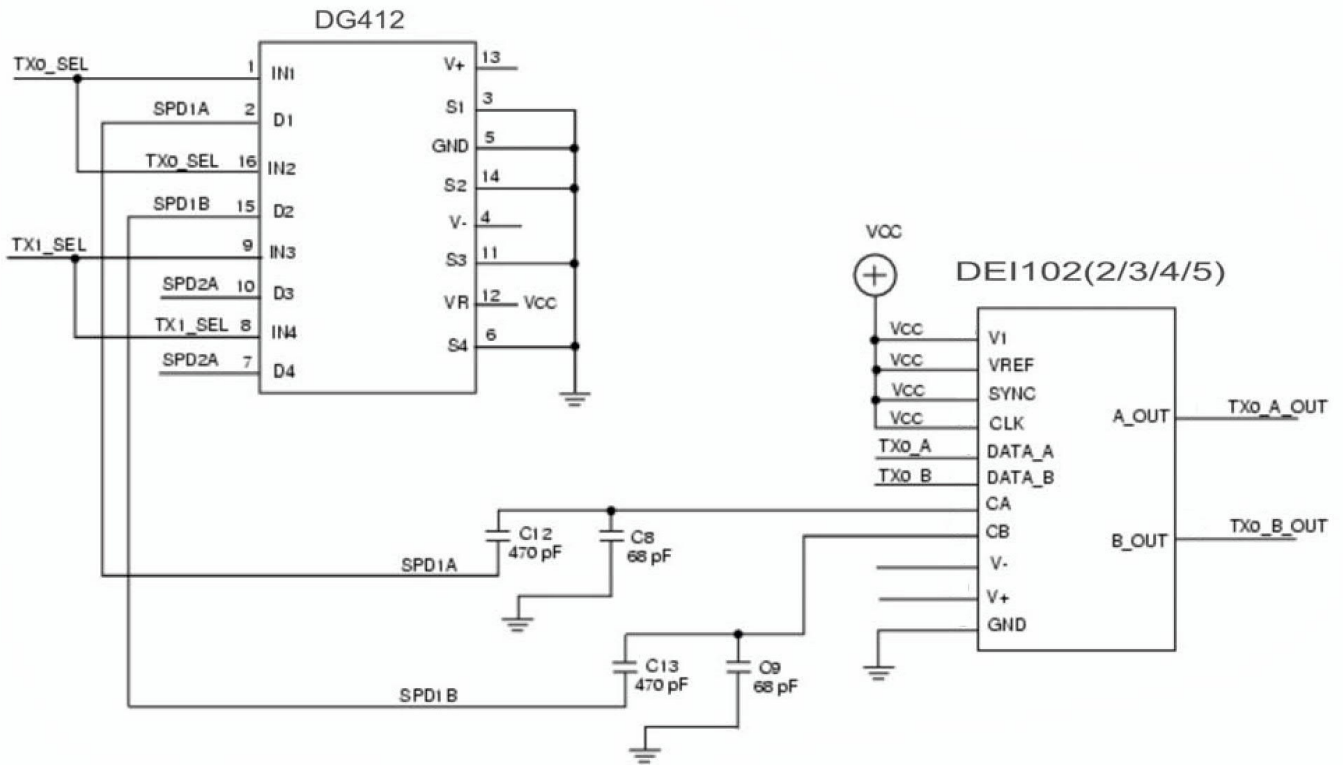


Figure 6: Typical Circuitry- Switching Capacitors For High-Speed/Low-Speed Operation

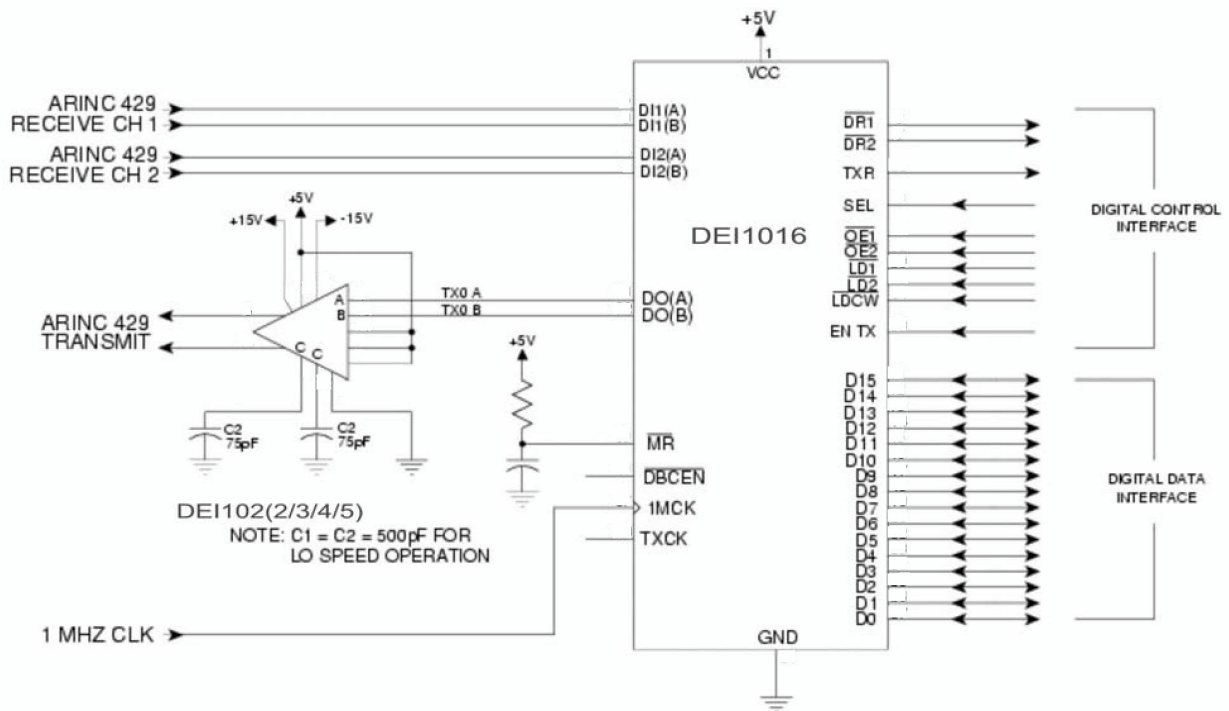
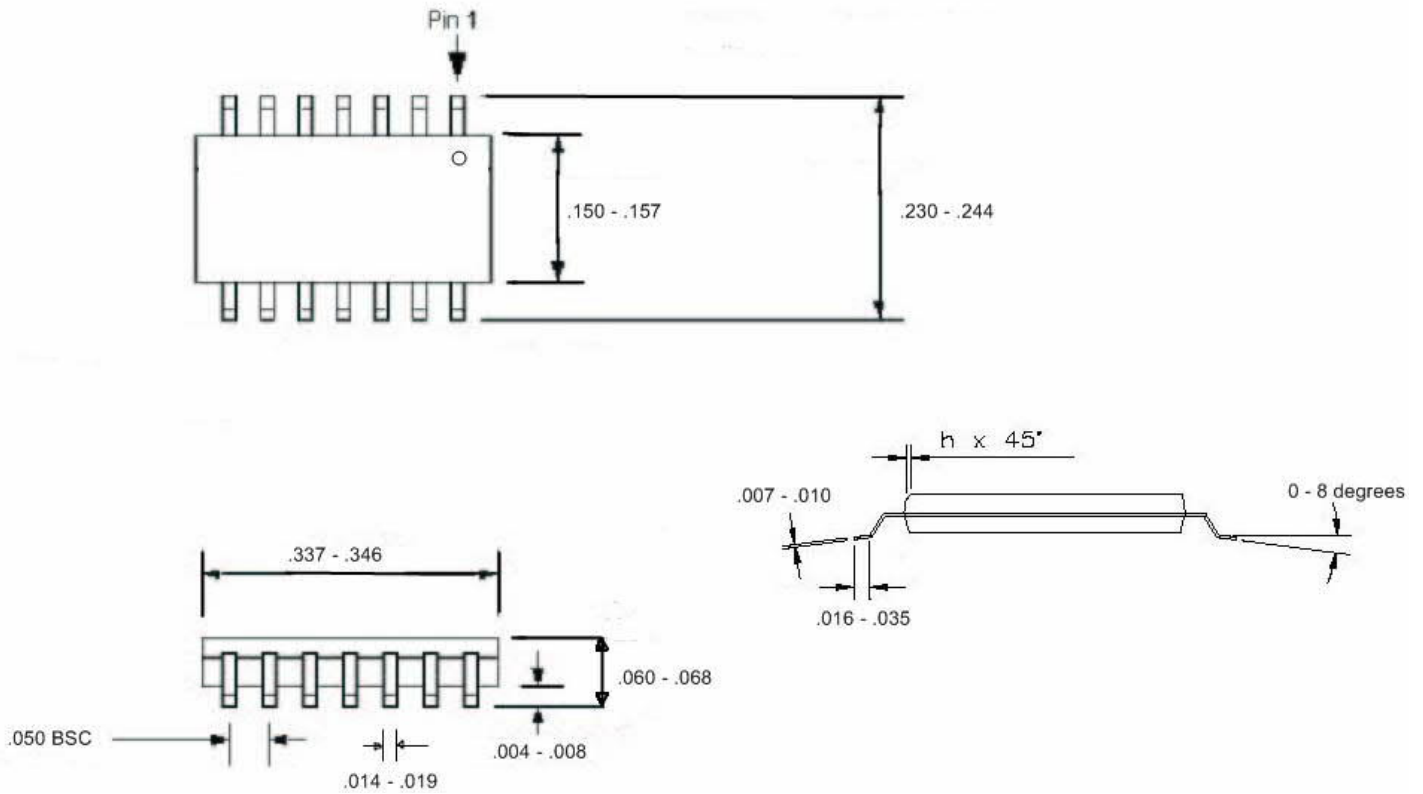


Figure 7: Typical Transceiver/Line Driver Interconnect Configuration



## Package Information

Table 9: Package Characteristics	
Characteristic	Value
REFERENCE	14 SOIC NB G
<b>THERMAL RESISTANCE:</b>	
$\theta_{JA}$ (2 layer PCB)	115 °C/W
$\theta_{JA}$ (4 layer PCB with Power Planes)	88 °C/W
$\theta_{JC}$	37 °C/W
JEDEC MOISTURE SENSITIVITY LEVEL (MSL)	MSL 1 / 260°C
LEAD FINISH MATERIAL / JEDEC Pb-free CODE	NiPdAu e4
Pb-Free DESIGNATION	RoHS Compliant
JEDEC REFERENCE	MS-012-AB



**Figure 8: Mechanical Outline**

Table 10: Screening Process	
SCREENING	METHODS
ELECTRICAL TEST:	
ROOM TEMPERATURE	100%
HIGH TEMPERATURE	100% @ +125 °C
LOW TEMPERATURE	0.65% AQL@-55°C

Table 11: Ordering Information					
DEI PART NUMBER	MARKING (1)	PACKAGE	TEMPERATURE RANGE	OUTPUT RESISTOR	OUTPUT FUSE
DEI1022-G	DEI1022 E4	14 SOIC NB G	-55 / +85 °C	37.5 Ω	NO
DEI1023-G	DEI1023 E4	14 SOIC NB G	-55 / +85 °C	37.5 Ω	YES
DEI1024-G	DEI1024 E4	14 SOIC NB G	-55 / +85 °C	0 Ω	NO
DEI1025-G	DEI1025 E4	14 SOIC NB G	-55 / +85 °C	0 Ω	YES

Notes:  
1. All packages marked with Lot Code and Date Code. "E4" after Date Code denotes Pb Free category.

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